

Electronic Patent Application Fee Transmittal

Application Number:	10722288			
Filing Date:	25-Nov-2003			
Title of Invention:	THERMAL INTERFACE MATERIAL AND SOLDER PREFORMS			
First Named Inventor/Applicant Name:	Brian G. Lewis			
Filer:	Andrew C. Wegman/Valarie McLaurin			
Attorney Docket Number:	CEDA 7000.5			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Claims in excess of 20	1202	31	50	1550
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				1550